SCBS203D - AUGUST 1992 - REVISED JANUARY 1998

- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- Two 8-Bit Back-to-Back Registers Store **Data Flowing in Both Directions**
- **Noninverting Outputs**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

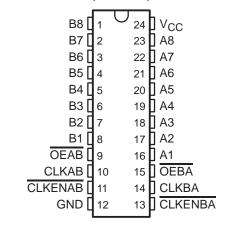
description

The 'ABT2952A transceivers consist of two 8-bit back-to-back registers that store data flowing in both directions between two bidirectional buses. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input provided that the clock-enable (CLKENAB or CLKENBA) input is low. Taking the output-enable (OEAB or OEBA) input low accesses the data on either port.

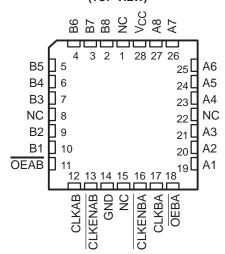
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT2952A is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT2952A is characterized for operation from -40°C to 85°C.

SN54ABT2952A . . . JT OR W PACKAGE SN74ABT2952A...DB, DW, PW, OR NT PACKAGE (TOP VIEW)



SN54ABT2952A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC is a trademark of Texas Instruments Incorporated



SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

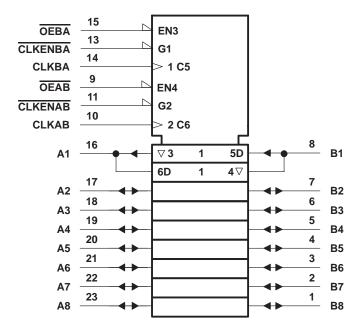
SCBS203D - AUGUST 1992 - REVISED JANUARY 1998

FUNCTION TABLE†

	INPUTS									
CLKENAB	CLKAB	Α	В							
Н	Х	L	Χ	в ₀ ‡ в ₀ ‡						
Х	H or L	L	Χ	в ₀ ‡						
L	\uparrow	L	L	L						
L	\uparrow	L	Н	Н						
Х	Χ	Н	Χ	Z						

[†]A-to-B data flow is shown; B-to-A data flow is similar, but uses CLKENBA, CLKBA, and OEBA.

logic symbol§



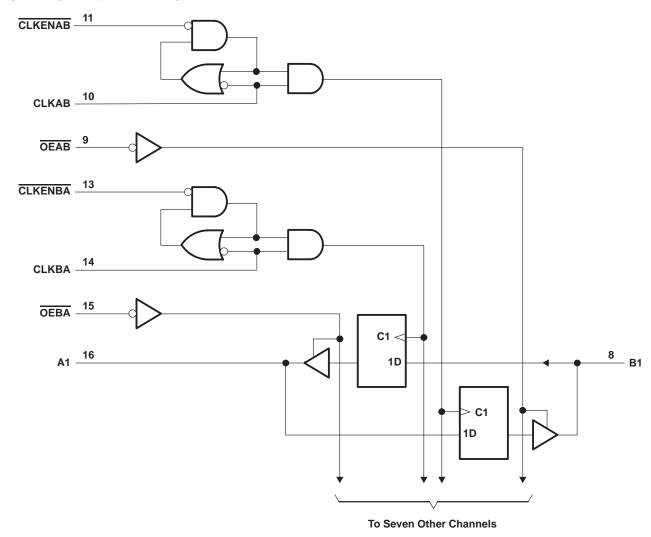
§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.



[‡]Level of B before the indicated steady-state input conditions were established

SCBS203D - AUGUST 1992 - REVISED JANUARY 1998

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCBS203D - AUGUST 1992 - REVISED JANUARY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I (except I/O ports) (see Note 1)	
Voltage range applied to any output in the high or power	er-off state, V _O –0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT2	2952A 96 mA
SN74ABT2	2952A
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	
Package thermal impedance, θ _{JA} (see Note 2): DB package	ckage 104°C/W
DW pa	ackage 81°C/W
NT pag	ckage 67°C/W
PW pa	ckage 120°C/W
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT	2952A	SN74ABT2952A		UNIT	
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V	
V _{IL}	Low-level input voltage					0.8	V
VI	Input voltage		0	VCC	0	VCC	V
IOH	High-level output current			-24		-32	mA
IOL	Low-level output current		48		64	mA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCBS203D - AUGUST 1992 - REVISED JANUARY 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST C	T	A = 25°C	;	SN54AB	Г2952А	SN74AB1	2952A	UNIT	
PA	RAMEIER	l lesi c	ONDITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	I _{OH} = -3 mA	2.5			2.5		2.5		
\/a		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		٧
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
VOL		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			٧
		VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$			0.55*				0.55	V
V _{hys}				100						mV	
	Control inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		±1		±1	μΑ
Ħ	A or B ports	VCC = 5.5 V,	AL = ACC OL GIAD			±100		±100		±100	μΑ
lozh [‡]		$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 \text{ V}$			50*		10		50	μΑ
l _{OZL} ‡		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			- 50*		-10		-50	μΑ
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100*				±100	μΑ
ICEX		V _C C = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ
ΙΟ§		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
		$V_{CC} = 5.5 \text{ V},$	Outputs high		1	250		250		250	μΑ
Icc	A or B ports	$I_O = 0$, $V_I = V_{CC}$ or	Outputs low		24	35		35		35	mA
		GND	Outputs disabled		0.5	250		250		250	μΑ
ΔICC¶		V _{CC} = 5.5 V, On Other inputs at V			1.5		1.5		1.5	mA	
C _i	Control inputs $V_I = 2.5 \text{ V or } 0.5 \text{ V}$			3.5						pF	
C _{io}	$V_{O} = 2.5 \text{ V or } 0.5 \text{ V}$			7.5						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				V _{CC} = 5 V, T _A = 25°C		SN54ABT2952A		SN74ABT2952A		UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX				
fclock	Clock frequency	0	150	0	150	0	150	MHz			
t _W	Pulse duration, CLK high or low					3.3		3.3		ns	
		A or B	High or low	2.5		3		2.5		no	
t _{su}	Setup time before CLK↑	CLKEN	High or low	3		3		3		ns	
.	Hold time after CLK↑	A or B		1.5		1.5		1.5		20	
t _h	Hold time after CLK	CLKEN		2		2		2		ns	



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡]The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

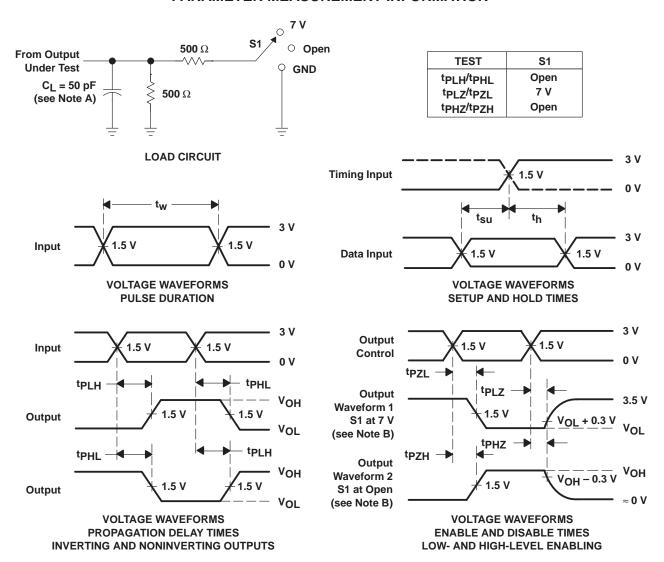
SCBS203D - AUGUST 1992 - REVISED JANUARY 1998

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT2952A		SN74AB1	UNIT	
	(INFOT)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
fmax			150			150		150		MHz
^t PLH	CLKAB or CLKBA	B or A	2	3.3	5.2	2	6.3	2	5.9	ns
^t PHL	CLRAB OF CLRBA	BULA	2.5	4	6.1	2.5	6.8	2.5	6.3	115
^t PZH	OFDA ** OFAR	A or B	1.5	3.2	4.7	1.5	5.7	1.5	5.6	nc
t _{PZL}	OEBA or OEAB	AUIB	2	3.7	5.7	2	6.7	2	6.6	ns
^t PHZ	OFDA OFAR	A or B	1.5	3.5	5.1	1.5	6.5	1.5	6.4	no
^t PLZ	OEBA or OEAB	AUID	1.5	3.4	5.9	1.5	6.7	1.5	6.2	ns



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

www.ti.com 4-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9308602QLA	Active	Production	CDIP (JT) 24	15 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9308602QL A SNJ54ABT2952AJ T
SN74ABT2952ADWR	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2952A
SN74ABT2952ADWR.B	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2952A
SNJ54ABT2952AJT	Active	Production	CDIP (JT) 24	15 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9308602QL A SNJ54ABT2952AJ T

⁽¹⁾ Status: For more details on status, see our product life cycle.

- (3) RoHS values: Yes, No. RoHS Exempt. See the TI RoHS Statement for additional information and value definition.
- (4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

PACKAGE OPTION ADDENDUM

www.ti.com 4-Nov-2025

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ABT2952A, SN74ABT2952A:

● Catalog : SN74ABT2952A

Military: SN54ABT2952A

NOTE: Qualified Version Definitions:

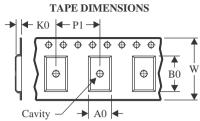
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 5-Dec-2023

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

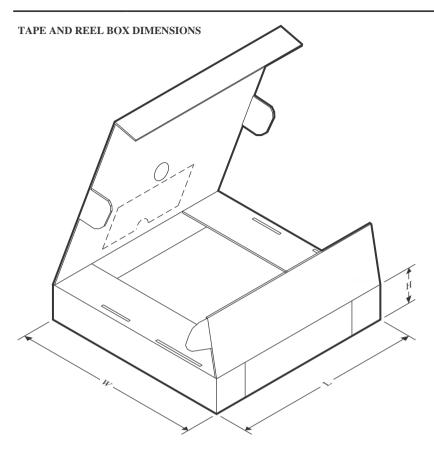


*All dimensions are nominal

	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ĺ	SN74ABT2952ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 5-Dec-2023



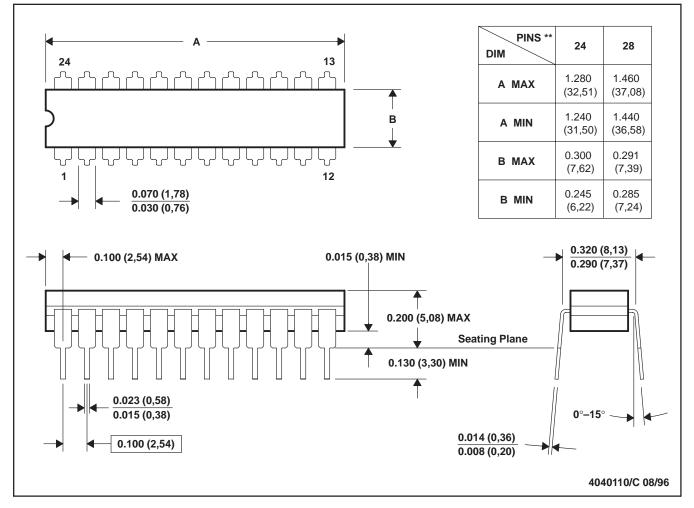
*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
I	SN74ABT2952ADWR	SOIC	DW	24	2000	350.0	350.0	43.0	

JT (R-GDIP-T**)

24 LEADS SHOWN

CERAMIC DUAL-IN-LINE

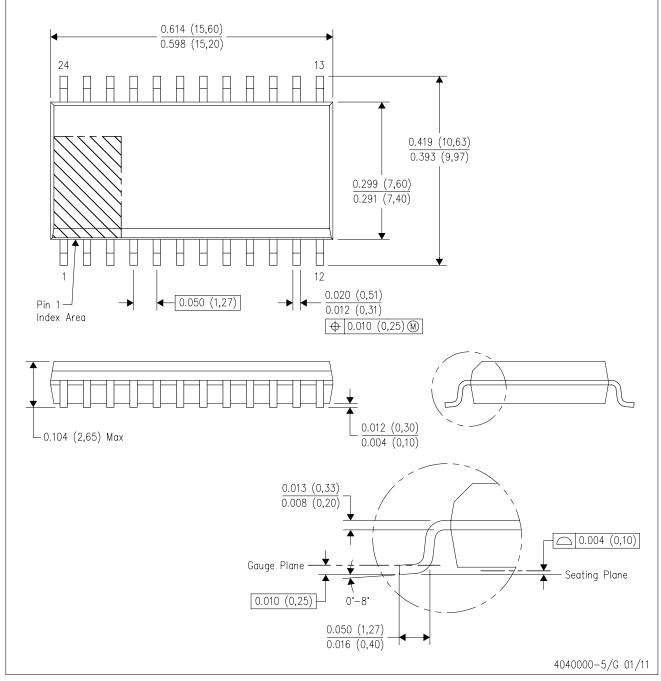


NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



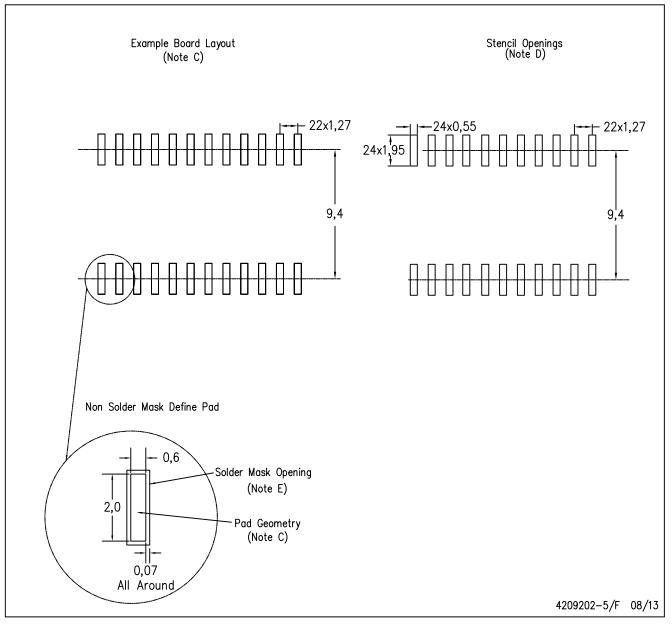
NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale, TI's General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025